

P-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- ☒ Surface-mounted package
- ☒ Advanced trench cell design

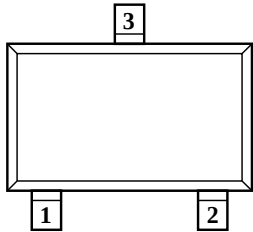
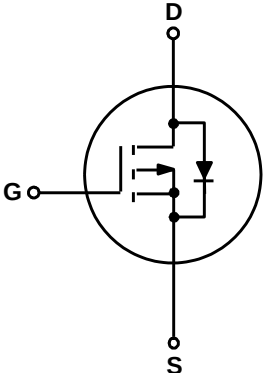
1.2 Applications

- ☒ Portable appliances
- ☒ High speed switch
- ☒ Battery management
- ☒ Low power DC to DC Converter

1.3 Quick reference

- ☒ $BV \leq -30\text{ V}$
- ☒ $P_{tot} \leq 1.4\text{ W}$
- ☒ $I_D \leq -4.2\text{ A}$
- ☒ $R_{DS(ON)} \leq 65\text{ m}\Omega @ V_{GS} = -4.5\text{ V}$
- ☒ $R_{DS(ON)} \leq 85\text{ m}\Omega @ V_{GS} = -2.5\text{ V}$

2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Gate(G)	 Top View SOT23-3L	
2	Source(S)		
3	Drain(D)		

3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	$T_A = 25\text{ }^{\circ}\text{C}$	- 30	-	V
V_{GS}	Gate-Source Voltage	$T_A = 25\text{ }^{\circ}\text{C}$	-	± 12	V
I_D^*	Drain Current	$T_A = 25\text{ }^{\circ}\text{C}, V_{GS} = -10\text{ V}$	-	- 4.2	A
		$T_A = 100\text{ }^{\circ}\text{C}, V_{GS} = -10\text{ V}$	-	- 3.7	A
$I_{DM}^{*,**}$	Pulsed Drain Current	$T_A = 25\text{ }^{\circ}\text{C}, V_{GS} = -10\text{ V}$	-	- 20	A
P_{tot}	Total Power Dissipation	$T_A = 25\text{ }^{\circ}\text{C}$	-	1.4	W
T_{stg}	Storage Temperature		- 55	150	$^{\circ}\text{C}$
T_J	Junction Temperature		- 55	150	$^{\circ}\text{C}$
I_S	Diode Forward Current	$T_A = 25\text{ }^{\circ}\text{C}$	-	- 4.2	A
$R_{\theta JA}^*$	Thermal Resistance- Junction to Ambient		-	150	$^{\circ}\text{C} / \text{W}$

Notes :

* Surface Mounted on 1 in² pad area, $t \leq 10\text{ sec}$

** Pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$

4. Marking Information

Product Name	Marking
KJ3401A	3401

5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
KJ3401A	SOT23-3L			3000	

Note: KUAJIEXIN defines “ Green ” as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC / JEDEC J-STD-020C)

6. Electrical Characteristics (T_A = 25 °C Unless Otherwise Noted)

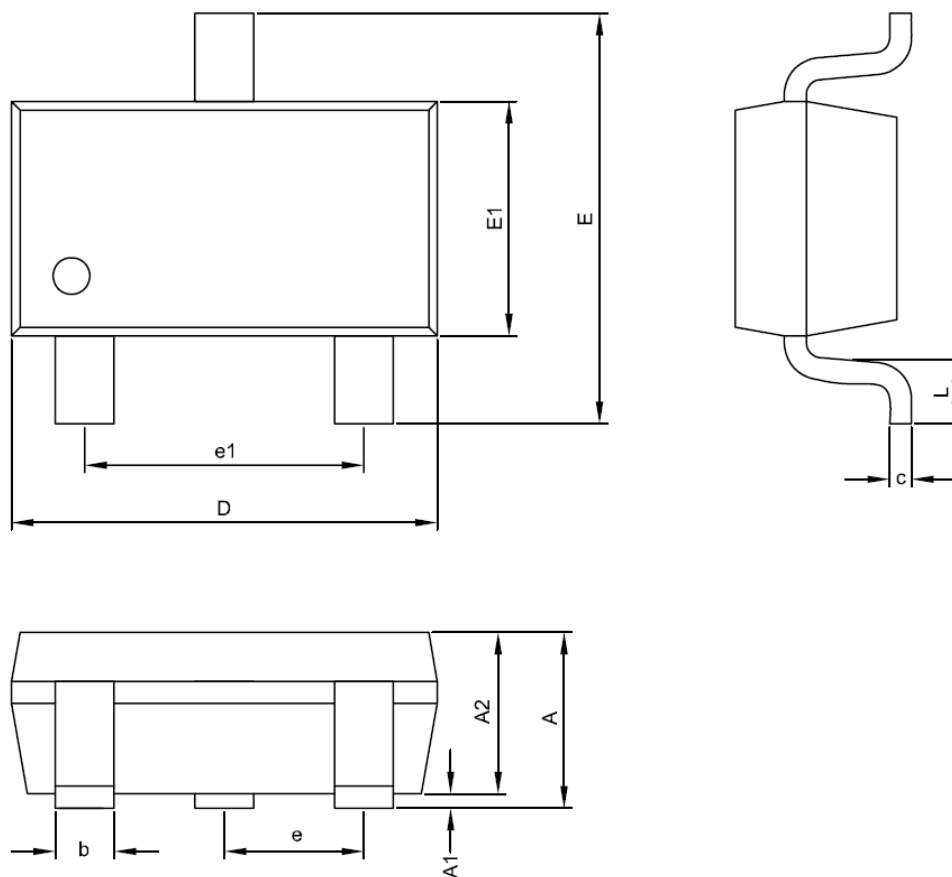
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _{DS} = - 250 μA	- 30	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _{DS} = - 250 μA	- 0.5	- 0.83	- 1.3	V
I _{DSS}	Drain Leakage Current	V _{DS} = - 24 V, V _{GS} = 0 V	-	-	- 1	μA
		T _J = 85 °C	-	-	- 30	μA
I _{GSS}	Gate Leakage Current	V _{GS} = ± 12 V, V _{DS} = 0 V	-	-	± 100	nA
R _{DS(ON)} ^a	On-State Resistance	V _{GS} = - 4.5 V, I _{DS} = - 3 A	-	53	65	
		V _{GS} = - 2.5 V, I _{DS} = - 2 A	-	73	85	
Diode Characteristics						
V _{SD} ^a	Diode Forward Voltage	I _{SD} = - 4 A, V _{GS} = 0 V	-	- 0.83	- 1.3	V
t _{rr}	Reverse Recovery Time	I _{SD} = - 4 A, dI _{SD} /dt = 100 A/μs	-	30	-	ns
Q _{rr}	Reverse Recovery Charge		-	2.7	-	nC
Dynamic Characteristics ^b						
C _{iss}	Input Capacitance	V _{GS} = 0 V, V _{DS} = -15 V Frequency = 1 MHz	-	880	-	pF
C _{oss}	Output Capacitance		-	105	-	
C _{rss}	Reverse Transfer Capacitance		-	65	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} = - 15 V, V _{GEN} = - 10 V, R _G = 6 Ω, R _L = 3.75 Ω, I _{DS} = - 4 A	-	7	-	ns
t _r	Turn-on Rise Time		-	3	-	
t _{d(off)}	Turn-off Delay Time		-	30	-	
t _f	Turn-off Fall Time		-	12	-	
Gate Charge Characteristics ^b						
Q _g	Total Gate Charge	V _{GS} = - 10 V, V _{DS} = - 15 V, I _{DS} = - 4 A	-	8.5		nC
Q _{gs}	Gate-Source Charge		-	1.8		
Q _{gd}	Gate-Drain Charge		-	2.7		

Notes : a : Pulse test ; pulse width ≤ 300 μs, duty cycle ≤ 2 %

b : Guaranteed by design, not subject to production testing

8. Package Dimensions

SOT23-3L



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	1.00	1.45
A1	0.00	0.15
A2	1.00	1.30
D	2.70	3.10
E	2.60	3.00
E1	1.50	1.70
c	0.08	0.25
b	0.30	0.50
e	0.95 BSC	
e1	1.90 BSC	
L	0.30	0.60